IRFN9240
JANTX2N7237U
JANTXV2N7237U
JANS2N7237U

IOR HiRel
An Infineon Technologies Company

POWER MOSFET SURFACE MOUNT(SMD-1)

200V, P-CHANNEL
REF: MIL-PRF-19500/595
HEXFET® MOSFET TECHNOLOGY

Product Summary

Part Number	RDS(on)	I_D
IRFN9240	0.51Ω	-11A

SMD-1

Description

HEXFET® MOSFET technology is the key to IR Hirel advanced line of power MOSFET transistors. The efficient geometry design achieves very low on-state resistance combined with high transconductance. HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, high energy pulse circuits, and virtually any application where high reliability is required. The HEXFET transistor's totally isolated package eliminates the need for additional isolating material between the device and the heatsink. This improves thermal efficiency and reduces drain capacitance.

Features

- Simple Drive Requirements
- Hermetically Sealed
- Surface Mount
- Dynamic dv/dt Rating
- Light Weight

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I_{D1} @ V_{GS} = -10V, T_C = 25°C	Continuous Drain Current	-11	A
I_{D2} @ V_{GS} = -10V, T_C = 100°C	Continuous Drain Current	-7.0	
I_{DM} @T_C = 25°C	Pulsed Drain Current ①	-44	
P_D @T_C = 25°C	Maximum Power Dissipation	125	W
	Linear Derating Factor	1.0	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy ②	500	mJ
I_{AR}	Avalanche Current ①	-11	A
E_{AR}	Repetitive Avalanche Energy ①	12.5	mJ
dv/dt	Peak Diode Recovery ③	-5.0	V/ns
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 150	°C
	Package Mounting Surface Temperature	300 (for 5 S)	
	Weight	2.6 (Typical)	g

For footnotes refer to the page 2.

Electrical Characteristics @ Tj = 25°C (Unless Otherwise Specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	-200	—	—	V	V_{GS} = 0V, I_D = -1.0mA
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	-0.2	—	V/°C	Reference to 25°C, I_D = -1.0mA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.51	Ω	V_{GS} = -10V, I_{D2} = -7.0A ④
		—	—	0.52		V_{GS} = -10V, I_{D1} = -11A ④
$V_{GS(th)}$	Gate Threshold Voltage	-2.0	—	-4.0	V	V_{DS} = V_{GS}, I_D = -250µA
Gfs	Forward Transconductance	4.0	—	—	S	V_{DS} = -15V, I_{D2} = -7.0A ④
I_{DSS}	Zero Gate Voltage Drain Current	—	—	-25	µA	V_{DS} = -160V, V_{GS} = 0V
		—	—	-250		V_{DS} = -160V, V_{GS} = 0V, T_J =125°C
I_{GSS}	Gate-to-Source Leakage Forward	—	—	-100	nA	V_{GS} = -20V
	Gate-to-Source Leakage Reverse	—	—	100		V_{GS} = 20V
Q_G	Total Gate Charge	—	—	60	nC	I_{D1} = -11A
Q_{GS}	Gate-to-Source Charge	—	—	15		V_{DS} = -100V
Q_{GD}	Gate-to-Drain ('Miller') Charge	—	—	38		V_{GS} = -10V
$t_{d(on)}$	Turn-On Delay Time	—	—	35	ns	V_{DD} = -100V
tr	Rise Time	—	—	85		I_{D1} = -11A
$t_{d(off)}$	Turn-Off Delay Time	—	—	85		R_G = 9.1Ω
t_f	Fall Time	—	—	65		V_{GS} = -10V
Ls +L_D	Total Inductance	—	4.0	—	nH	Measured from the center of drain pad to center of source pad
C_{iss}	Input Capacitance	—	1200	—	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	—	570	—		V_{DS} = -25V
C_{rss}	Reverse Transfer Capacitance	—	81	—		f = 1.0MHz

Source-Drain Diode Ratings and Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	—	—	-11	A	
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	-44		
V_{SD}	Diode Forward Voltage	—	—	-5.0	V	T_J = 25°C, I_S = -11A, V_{GS} = 0V④
t_{rr}	Reverse Recovery Time	—	—	440	ns	T_J = 25°C, I_F = -11A, V_{DD} ≤ -30V
Q_{rr}	Reverse Recovery Charge	—	—	7.2	µC	di/dt = -100A/µs ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Thermal Resistance

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$R_{\theta JC}$	Junction-to-Case	—	—	1.0	°C/W	
$R_{\theta J-PCB}$	Junction to PC Board	—	4.0	—		Soldered to a copper-clad PC board

Footnotes:

① Repetitive Rating; Pulse width limited by maximum junction temperature.

② V_{DD} = -50V, starting T_J = 25°C, L = 8.3mH, Peak I_L = -11A, V_{GS} = -10V.

③ I_{SD} ≤ -11A, di/dt ≤ -150A/µs, V_{DD} –200V, T_J ≤ 150°C.

④ Pulse width ≤ 300 µs; Duty Cycle ≤ 2%

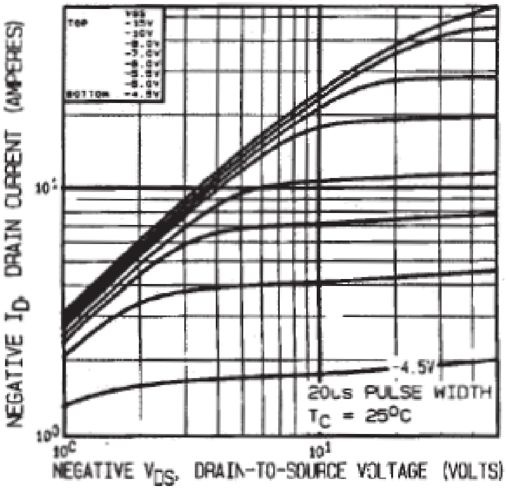


Fig 1. Typical Output Characteristics

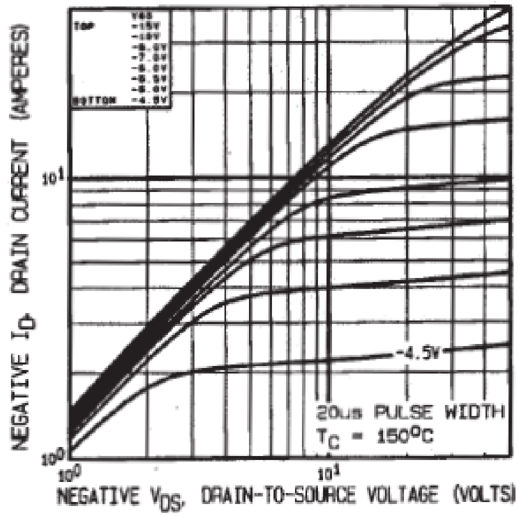


Fig 2. Typical Output Characteristics

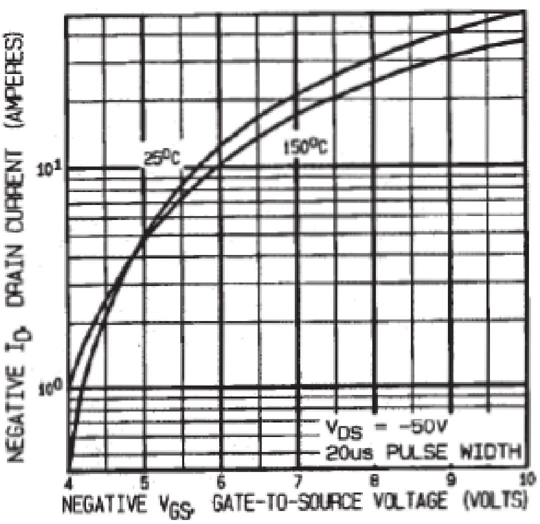


Fig 3. Typical Transfer Characteristics

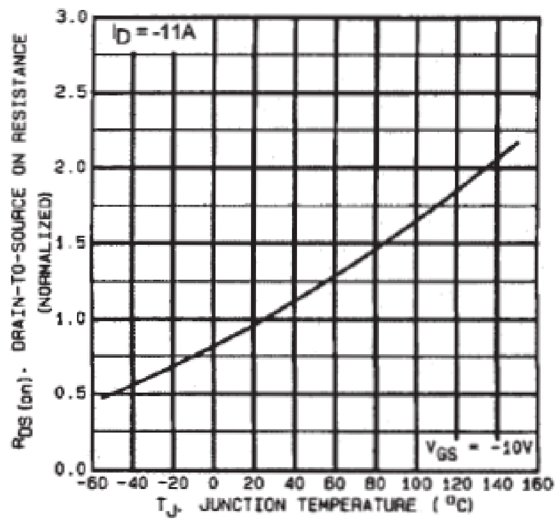


Fig 4. Normalized On-Resistance Vs. Temperature

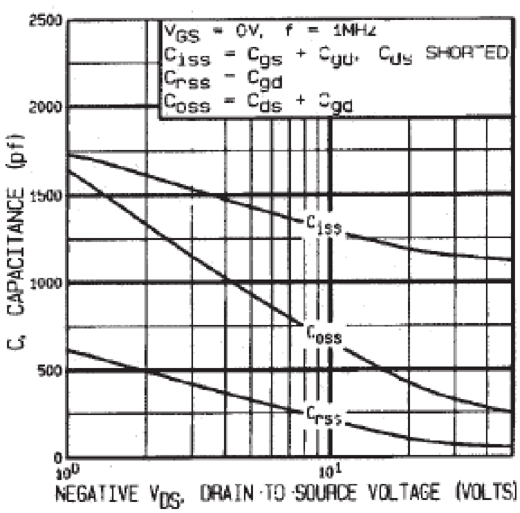


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

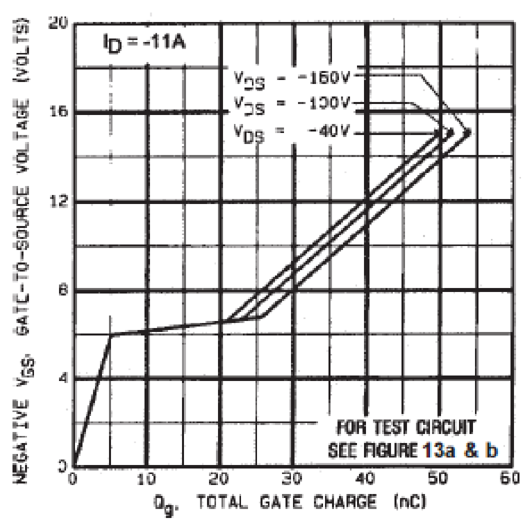


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

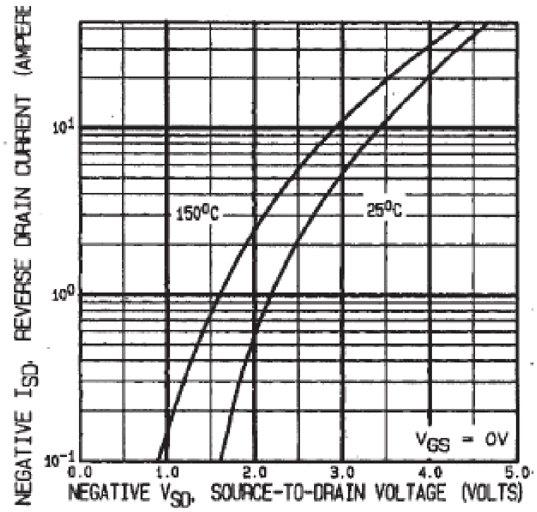


Fig 7. Typical Source-Drain Diode Forward Voltage

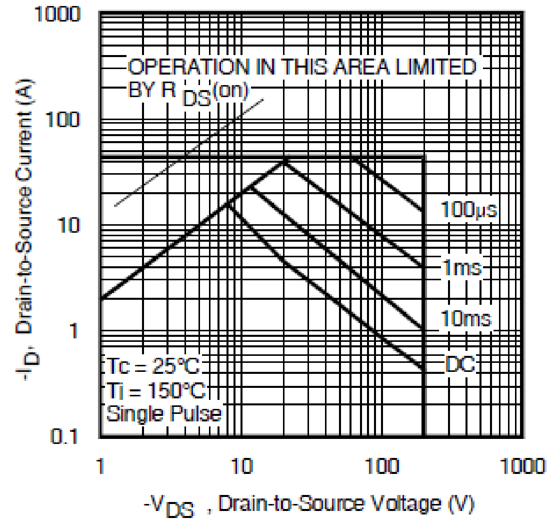


Fig 8. Maximum Safe Operating Area

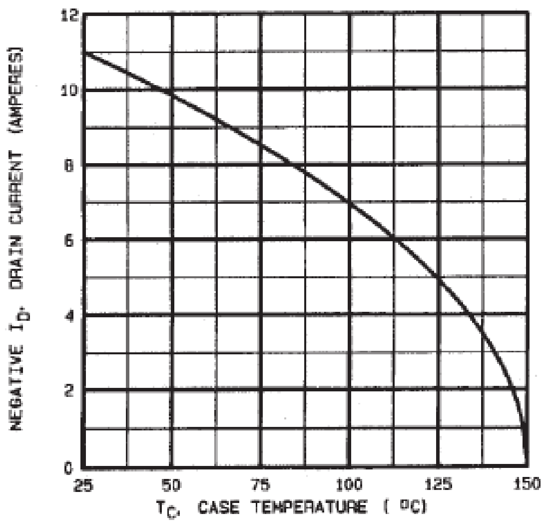


Fig 9. Maximum Drain Current Vs.Case Temperature

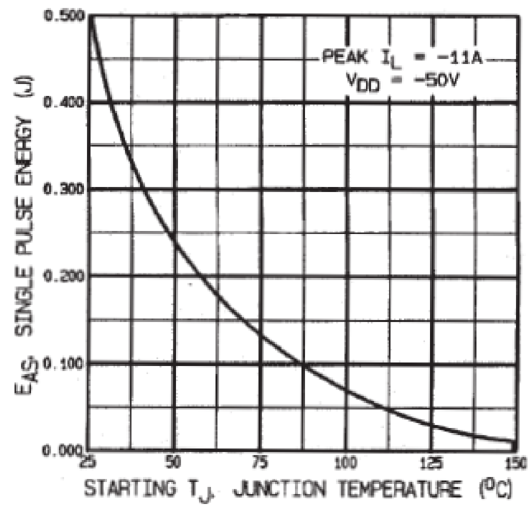


Fig 10. Maximum Avalanche Energy Vs. Drain Current

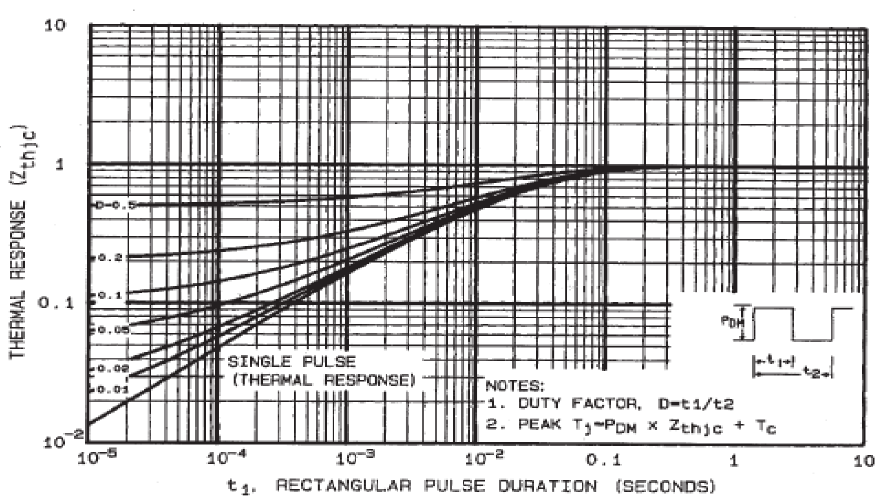


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

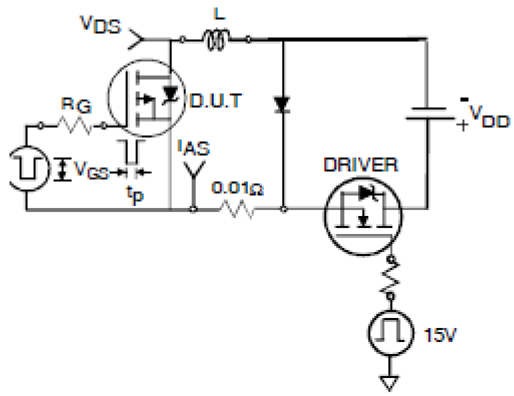


Fig 12a. Unclamped Inductive Test Circuit

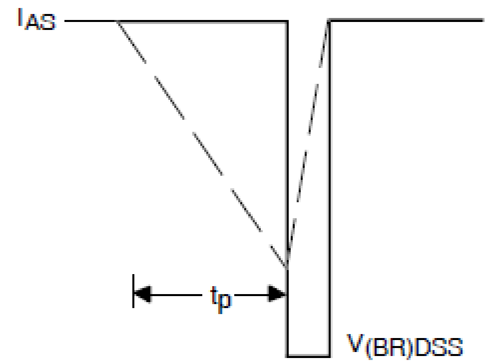


Fig 12b. Unclamped Inductive Waveforms

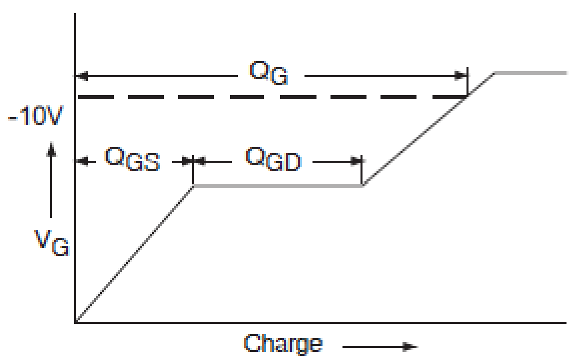


Fig 13a. Gate Charge Waveform

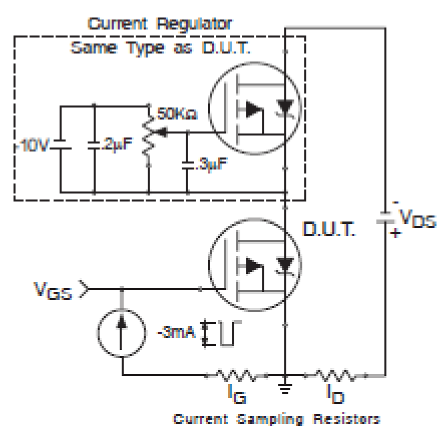


Fig 13b. Gate Charge Test Circuit

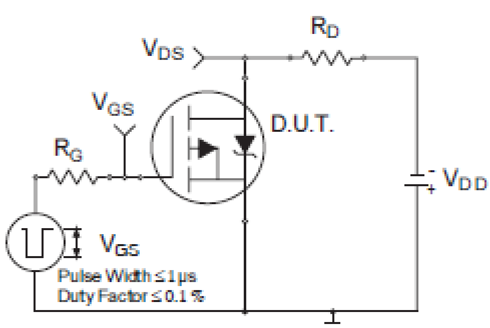


Fig 14a. Switching Time Test Circuit

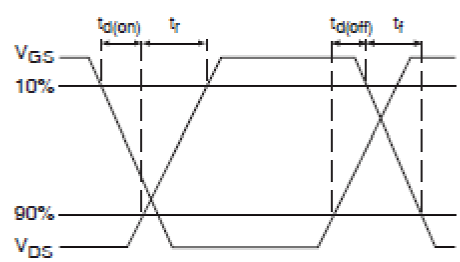
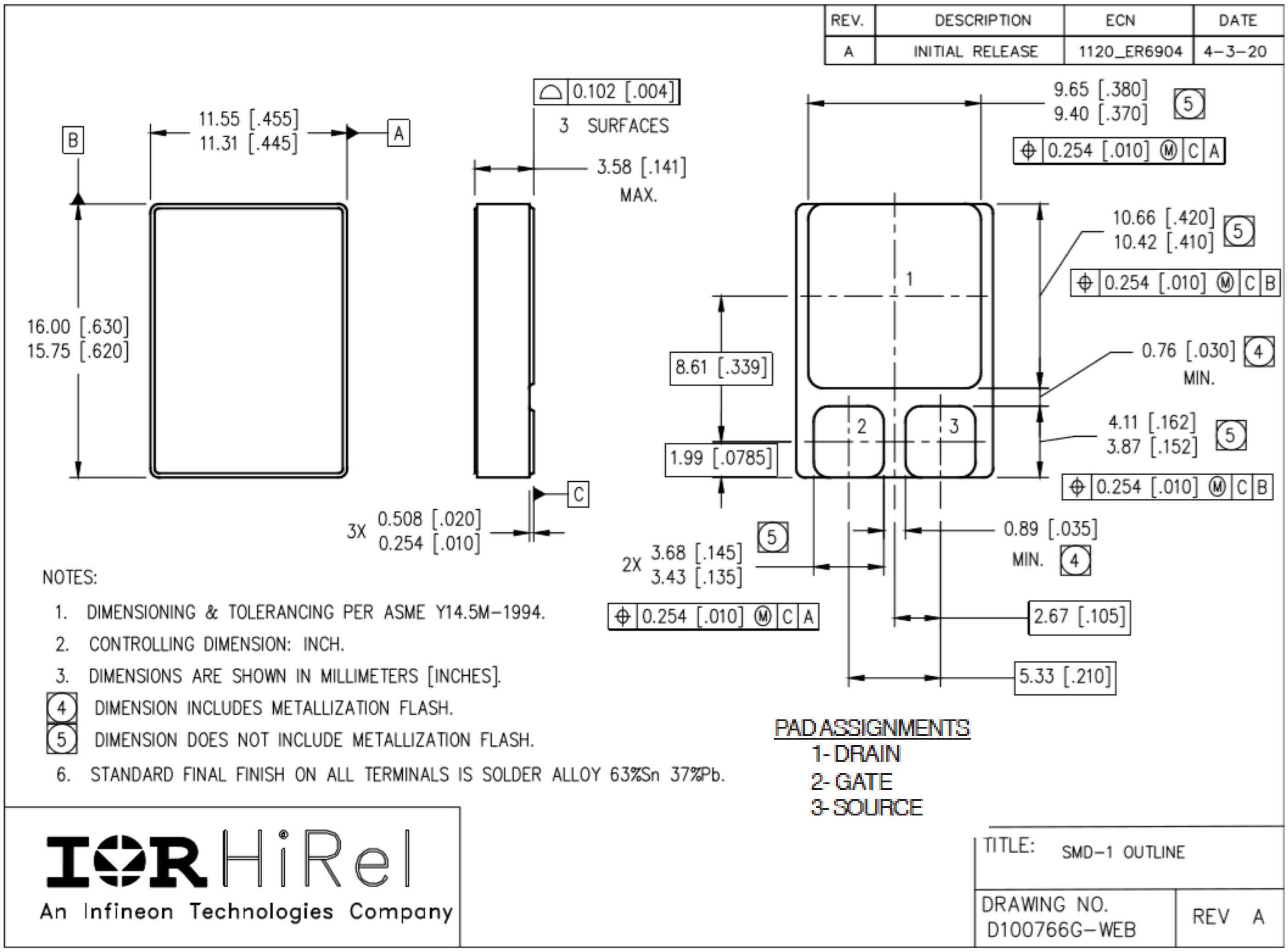


Fig 14b. Switching Time Waveforms

Note: For the most updated package outline, please see the website: [SMD-1]

Case Outline and Dimensions - SMD-1



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